Reconfigurable THz Filters Using Phase-Change Material and Integrated Heater

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Abstract—We report the design, fabrication, and measurements of reconfigurable terahertz (THz) filters using vanadium dioxide (VO_2) phase-change material (PCM), which undergoes a transition between an insulator and metal phase at 68 °C (\sim 341 K). The filters are made of frequency selective surfaces (FSS) and heater are integrated for VO_2 excitation. Two THz spatial filters are developed. A broadband on/off filter at 0.35 THz is demonstrated with 20 dB change in transmission between the on and off states. Then, a reconfigurable stopband FSS filter with tunable rejection from 0.75 to 0.55 THz is presented. The latter shows a peak with rejection of more than 90%. The two states of both filters are achieved at relatively low temperature of 68 °C, making them suitable for practical applications. Comparisons between simulation and measurement show excellent agreement for both 0.35 THz on/off filter and 0.75 to 0.55 THz tunable filters.

Index Terms—Periodic structures, phase-change materials (PCMs), reconfigurable, terahertz (THz) filter, vanadium dioxide (VO_2).

I. INTRODUCTION

ERAHERTZ (THz) bands are of interest due to their unique applications in imaging and sensing, material characterization, space sciences, and short-range communications [1]–[8]. However, lack of fabricable components in this frequency range remains a challenge. Specifically, tunable filters are highly desired with reconfiguration. These filters are used to improve signal-to-noise ratio, block unwanted surrounding power, and allow for better detection of the desired field.

In this paper, we consider phase-change materials (PCMs) as a switching mechanism for the reconfigurable frequency selective surfaces (FSS) filter. PCMs refer to materials that exhibit the transition from dielectrics to conductors driven by external excitations, such as heat, electric field, optically injected charges, external stress or pressure [9], [10]. Various PCMs have been considered [9]–[13], corresponding to a wide range of transition temperatures. However, most of these PCMs [12] have their transition temperatures significantly below room temperature, implying that a cooling system is needed for triggering the switch. For all practical purposes, we require PCMs where a heater is employed.

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Among various PCMs, vanadium dioxide (VO_2) is one such material that undergoes a transition between an insulator and metal phases at 68 °C (\sim 341 K), which is closest to room temperature. Importantly, PCM can be easily integrated into microsystems. The latter property makes VO_2 PCMs attractive for reconfigurable filters [14], [15]. Though there are several studies of the reconfigurable applications using PCM [14]–[26], none of them employs build-in temperature control [15]. In this paper, an integrated heater is introduced to enable thermal excitation of VO_2 in a practical manner. Reconfiguration is also demonstrated achieving tunability for THz FSS filters with the integrated heater. This controlled heater enhances the practical realization of this type of filters.

In this paper, two types of THz spatial filters are examined: 1) a broadband on/off filter; and 2) a frequency reconfigurable stopband filter. The integrated heater is designed to control the filter temperature without affecting the performance of the filter. The VO_2 thin-film process development is extensively discussed and measurements are provided that verify the VO_2 performance in both states.

II. DESIGNS

Several high-performance THz filters are commercially available. However, their frequency response is fixed and do not provide a tunable frequency selectivity. There is also interest in achieving controllable bandpass and bandstop filter characteristics. FSS, which are periodic, planar, and generally consist of metallic elements on dielectric layers, is considered here as a THz filter since it shows bandpass or bandstop characteristic based on its geometry [8], [27]–[31]. To achieve the reconfiguration, VO₂ thin film is introduced within the FSS structure. The film can be deposited onto a substrate or inserted as part of the structure. The challenge is to minimize losses and optimize overall filter performance by sharpening the roll-off response curves of the FSS filter.

Here, we discuss two designs for reconfigurable THz filter by using VO_2 thin film to:

- reconfigure THz filters as ON/OFF filter at specific center frequency;
- 2) reconfigure THz filters as frequency shifting stopband filter.

A. Broadband ON/OFF Filter Design

Since the element type (geometry), substrates, superstrate, and interelement spacing play a significant role in the FSS's performance, the filter unit cell was carefully optimized. To

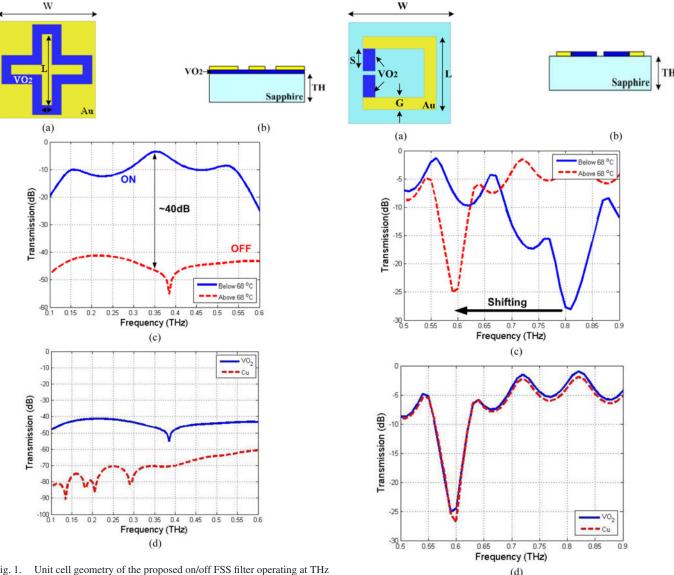


Fig. 1. Unit cell geometry of the proposed on/off FSS filter operating at THz frequencies. (a) Top view. (b) Side view. (c) Simulated transmission response. (d) Comparison of VO_2 to Cu at off stage.

Fig. 2. Unit cell geometry of the proposed frequency shifting FSS filter operating at THz frequencies. (a) Top view. (b) Side view. (c) Simulated transmission response. (d) Comparison of VO_2 to Cu at conductor phase.

allow for sufficient design flexibility, a cross-loop FSS is chosen (shown in Fig. 1). For reconfiguration, VO_2 film is placed between the substrate and metal patterns as depicted in Fig. 1(b).

The geometry of the unit cell is illustrated in Fig. 1(a) and its dimensions were optimized using the full-wave simulation (Ansys HFSS). The frequency of interest for this design is 0.35 THz that lies in the low absorption atmospheric window with large available bandwidth [32]. The dimensions of this design are: unit cell size $W=150~\mu\mathrm{m}$, cross length $L=140~\mu\mathrm{m}$, and cross width $G=15~\mu\mathrm{m}$. Also, the substrate is a c-plane sapphire of thickness $(TH)=150~\mu\mathrm{m}$. The goal is to exploit the conductivity change of the VO $_2$ film from dielectric to conducting state as a function of temperature. Specifically at above \sim 68 °C, the VO $_2$ film becomes metallic and blocks the incoming wave. Therefore, the filter acts as a reflector (off state). This filter has two states (on/off) when the temperature is below/above \sim 68 °C. As shown in Fig. 1(a), 40 dB difference is achieved at

0.35 THz. Full-wave simulations [see Fig. 1(c)] demonstrate the concept. In Fig. 1(d), we have also compared the ohmic losses of VO_2 in the conductor phase to Cu (conductivity = 5.8×10^7 S/m) as the standard material. There is ~ 30 dB difference in transmission at off stage between VO_2 and Cu as expected due to lower conductivity of VO_2 .

B. Frequency Reconfigurable Stopband Design

As the second design, we considered a reconfigurable THz filter using a combination of VO_2 thin film and gold to form the FSS structure (hybrid design). The unit cell is depicted in Fig. 2 as a square loop with a gap at the left. One side of the square FSS unit cell is constructed of VO_2 films and serves to alter the filter's response when the VO_2 transitions through its

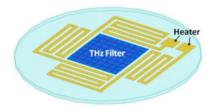


Fig. 3. Meander loop heater around the THz filter.

phases. The FSS was designed to operate between 0.5 to 0.9 THz. We note that the 0.6 and 0.8 THz frequency were chosen which are typical for THz security imagers used in atmospheric windows [33]. The dimension of the unit cell are: unit cell size $W=50~\mu\mathrm{m}$, C-shape length $L=36~\mu\mathrm{m}$, C-shape width $G=6~\mu\mathrm{m}$ with the VO₂ leg of $10~\mu\mathrm{m} \times 6~\mu\mathrm{m}$. Again c-plane sapphire of thickness $(TH)=430~\mu\mathrm{m}$ was used as a substrate.

The design in Fig. 2 achieved a stopband rejection that shifted from 0.8 to 0.6 THz when the VO_2 reached its metallic state (temperature > 68 °C). The filter is suitable for cases when large frequency shifting is required. Again, we compared the ohmic losses of VO_2 in conductor phase to Cu. There is a very small difference in transmission (\sim 2 dB) at the same frequency peak. As it can be seen from Figs. 1(a) and 2(a), the on/off filter structure has more metallization compared to the frequency shifting filter. Thus, the higher metallization causes lesser ohmic loss due to change in materials in unit cells.

C. Integrated Controlled Heater Design

Microheaters are well known in various microelectromechanical (MEMS) devices and microfluidic applications to provide several functionalities, i.e., physical and chemical sensors, pumping and chemical reactor [34]–[36]. In most of these designs, the heater is placed underneath the structure. However, for our unique application of the heater in spatial filters, it cannot be placed underneath for performance purpose. To actuate through the VO_2 state, a heater is introduced at the periphery of the FSS filter instead of underneath as shown in Fig. 3 [15].

The heater functions as resistive heating, which is the process where the input energy from electric current is converted into heat through resistive losses in the material. In designing the heater, it is important to have low power consumption, low thermal mass, fast transition, and temperature uniformity across where the device is operated. In our application, the temperature uniformity across the VO_2 in every unit cell is the most significant feature since we want to ensure that every unit cell in the array get activated at the same time.

To do so, different geometries of heater are studied: circular, square, and meander designs, were considered as shown in Fig 4. Multiphysics simulation tool (COMSOL) was used to study heater topologies. Gold was deposited to form the heater circuit with identical thickness as of the FSS pattern. This simplified fabrication process was chosen since the same step can be used for patterning the FSS structure. Again, 2'' diameter c-plane sapphire is used as the substrate. For heat control, different voltages were applied \times to achieve uniform temperature across the

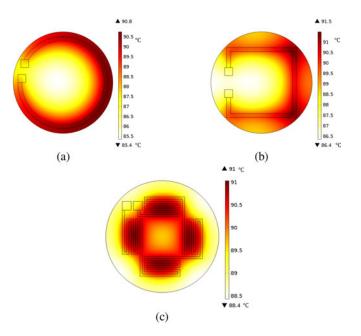


Fig. 4. Temperature contour of integrated heater surface with (a) circular, (b) square, and (c) meander designs.

 $0.8'' \times 0.8''$ center area of the design. We found that to achieve temperature of 85 to 91°C, the applied voltages of 2.1, 2.05, and 5 V are required for each heater design, respectively. As shown in Fig. 4, the circular and square heater designs are simpler and require lower voltage. However, the meander heater design provides more uniform temperature at the center since the geometry of the design is symmetric. This structure reduces the device area and help confining the heat at the center. Furthermore, the power consumption of each design is studied. The resistance of heater circuit of circular, square, and meander designs are 3.01, 2.93, and 18.45 Ω , respectively. Based on the applied voltage mentioned above, the power consumption of each heater design is calculated and obtained as 1.47, 1.44, and 1.35 W. As seen, the meander design provides lower power consumption even though it requires higher voltage. This is due to that the meander design reduces the overall device area with higher resistance of the heater compared to the other two designs. Hence, it was adopted for reconfiguration of our device.

III. FABRICATION

A. VO₂ Thin-Film Development

Before fabricating the FSS filter, high quality VO_2 thin film must be developed. Various VO_2 thin-film deposition techniques have been previously reported. They include pulsed laser deposition [37], sol-gel [38], RF reactive magnetron sputtering [39], and dc reactive magnetron sputtering [40]. For this paper, we employed dc reactive magnetron sputtering (AJA Orion) for VO_2 deposition. This approach provides conformal and uniform films on large sample area in a relatively low-cost batch process.

1) Deposition Process and Parametric Studies: The dc reactive magnetron sputtering with 99.5% Vanadium (V) target

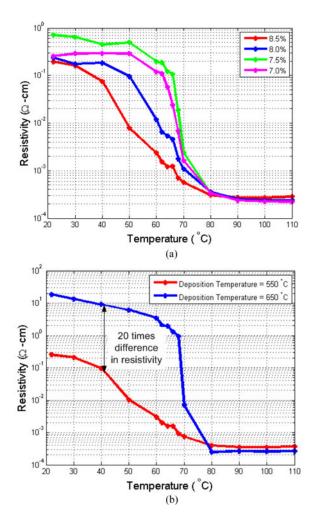


Fig. 5. (a) Resistivity versus excitation temperature for different Ar/O_2 injection ratio. (b) Resistivity versus excitation temperature for two deposition temperatures at 550 and 650 °C.

is used to deposit on 2'' c-plane (0001) sapphire substrate. In this system, argon (Ar) is used as a carrier and oxygen (O_2) is injected as reactive gas to create the oxide. There are several critical parameters in depositing VO_2 . Among them are: power, pressure, Ar/O_2 gas injection ratio, and deposition temperature.

Several attempts were made to achieve successful growth conditions. The Ar/O_2 injection ratio was studied and shown in Fig. 5(a) by varying the percentage of O_2 from 7% to 8.5%. It was observed that there is a small window for optimizing the resistivity ratio (i.e., ratio of resistivity below and above transition temperature). The deposition was performed at various temperatures ranging from 500 to 650 °C. As shown in Fig. 5(b), the deposition temperature impacts the resistivity ratio of the VO_2 film. Specifically, deposition at 650 °C provides about 20 times higher resistivity compared to 550 °C. This is important as we require as large as possible resistivity change. Finally, we have tuned the electrical and phase transition properties of our film to achieve largest conductivity change at \sim 68 °C. The VO_2 thin films have been grown with Ar/O_2 gas flow of 92.5/7.5 sccm. The deposition temperature is set to be 650 °C and the base

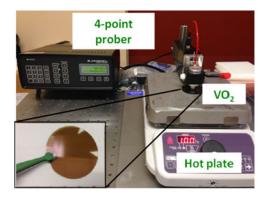


Fig. 6. Measurement setup (Inset: an example of VO_2 thin film deposited on a sapphire substrate) [20].

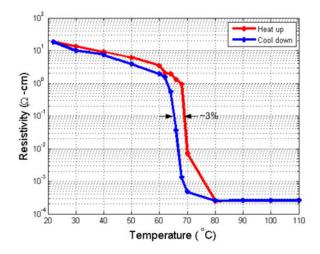


Fig. 7. Hysteresis loop of our developed VO₂ sample.

pressure before sputtering is controlled to be below 10^{-6} Torr. The pressure is kept constant at 10 mTorr throughout the deposition. The final $\rm VO_2$ film thickness is measured to be 80 nm for all design work.

- 2) Resistivity Measurement Setup: For measurement setup, the film is positioned on a hot plate and measurements are carried out as the temperature is varied in 2–10 °C steps. The overall resistivity measurement setup is shown in Fig. 6. A four-point probe (Jandel RM3000) was used to measure the sheet resistance of the film at dc. Then, the thickness of the film was measured using a Dektek profilometer. Finally, the resistivity of VO_2 versus temperature is determined from sheet resistance and thickness measurements.
- 3) Optimized VO_2 Thin-Film Resistivity: The resistivity ratio of our optimized VO_2 film is 7×10^4 times. This difference is observed as the temperature changes from 60 to 80 °C. As depicted in Fig. 7, our film shows low hysteresis of 3% during the heat up and cools down stages. The measured conductivity (σ) of our film at the two different temperatures is $\sigma=5.38~\mathrm{S/m}$ (dielectric phase) and $\sigma=3.77\times 10^5~\mathrm{S/m}$ (conductor phase), respectively.

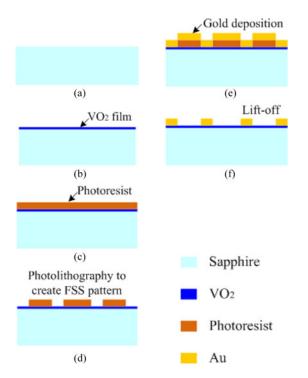


Fig. 8. Steps used to fabricate the broadband THz filter: (a) sapphire substrate, (b) $\rm VO_2$ sputtering deposition, (c) photoresist spinning, (d) photolithography, (e) Au deposition, and (f) lift-off.

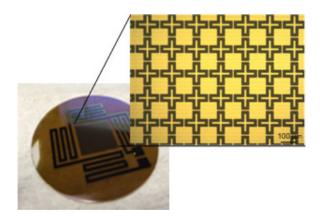


Fig. 9. Fabricated broadband on/off FSS filter with heater surrounding the FSS (inset: microscopic image).

B. Filters Fabrication

Upon achieving a high quality VO_2 thin-film deposition with 710^4 change in resistivity, we proceeded to realize two reconfigurable THz filters on a c-plane sapphire substrate. Standard photolithography, thin-film deposition, and lift-off techniques were used for fabricating on/off filter. The process is illustrated in Fig. 8. The final fabricated structure is shown in Fig. 9. First, the VO_2 thin film (80 nm thick) is deposited using dc sputtering as mentioned in the previous section. Next the standard photolithography step with image-reversal AZ5214E photoresist is used to pattern the periodic structure and heater. Then, a 200-nm thick gold (Au) layer is deposited using e-beam evaporator

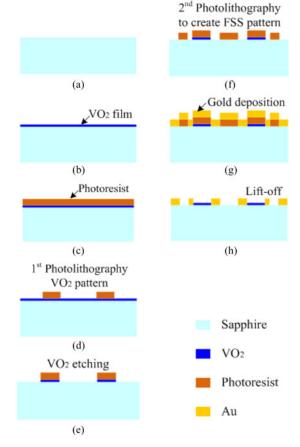


Fig. 10. Steps used to fabricate the frequency reconfigurable stopband THz filter: (a) sapphire substrate, (b) VO_2 sputtering deposition, (c) photoresist spinning, (d) first photolithography for pattering VO_2 legs, (e) VO_2 etching, (f) second photolithography to define FSS filter and heater structure, (g) Au deposition, and (h) lift-off process.

(CHA Solution) followed by a lift-off step to achieve the final structures.

Unlike the previous device, the frequency shifting stopband filter requires patterned VO_2 film instead of a blank thin film. Therefore, the following steps are followed: after the VO_2 deposition, the film is patterned using photolithography by S1813 positive photoresist. VO_2 film is then etched for 5 min in hydrogen peroxide (30% by weight) solution. After photoresist removal, a second lithography step is performed using imagereversal AZ5214E photoresist. This step gives the patterned VO_2 as depicted in Fig. 10. Then the 200-nm thick gold layer is deposited using e-beam evaporator. Finally, the pattern is achieved by a lift-off step (see Fig. 10). The frequency reconfigurable stopband filter is fabricated and shown in Fig. 11.

IV. MEASUREMENTS AND VALIDATION

The transmission of the fabricated THz filters was measured using a time-domain spectroscopy (TPS 3000 system, Teraview, Ltd.) at normal incidence ($\theta=0^{\circ}$). The schematics of the THz time-domain spectrometer (THz-TDS) in transmission mode is illustrated in Fig. 12(a) [8]. Using this setup, the broadband THz pulses were generated for the FSS filter excitation using a

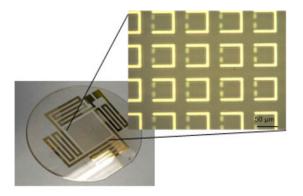


Fig. 11. Fabricated frequency reconfigurable stopband filter with heater surrounding the FSS (inset: microscopic image).

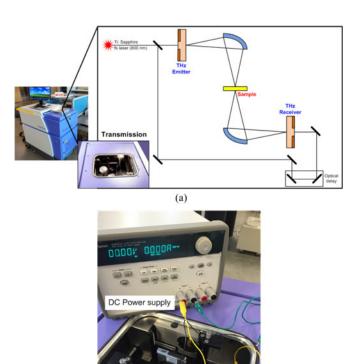


Fig. 12. (a) Schematics of THz time-domain spectrometer in transmission mode and (b) measurement setup.

photoconductive antenna. This antenna was excited via a pulsed near-infrared laser, which covers a frequency range of 0.06–3 THz. The incident THz excitation from the photoconductive antenna is focused through a curved reflector before incidence on the FSS sample. Transmission through the sample is then measured using the THz-TDS transmission gantry. During the process, voltage is applied to the heater with the range of 0–20 V. Power to the heater is controlled by varying the voltage to achieve two phases of VO₂. An aluminum sample holder is also used to help dissipating the heat. The overall measurement setup is shown in Fig. 12(b). The heater reached 70 °C after 18 V is

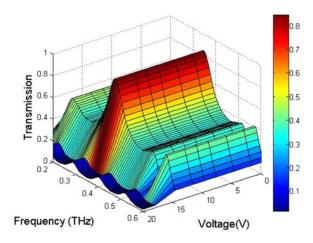


Fig. 13. Transmission of broadband on/off filter versus frequency (0.2–0.6 THz) for different voltages applied to the heater.

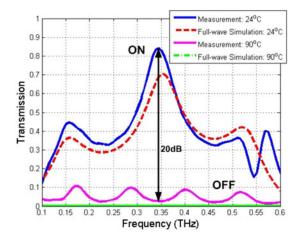


Fig. 14. Comparison of simulated and measured transmission response of the broadband on/off THz filter.

applied within 30 s and cooled down to room temperature within 45 s with the help of aluminum sample holder.

A. Broadband ON/OFF Filter Measurement

The transmission response of the filter in Fig. 9 is plotted in Fig. 13. This three-dimensional response gives the transmission itself as a function of applied voltage to the heater and the frequency of the excitation signal. It is shown that the transmission peak is at 0.35 THz [at room temperature (24 °C)] and drops nearly to 0.1 when voltage reaches 18 V at 70 °C.

Fig. 14 compares the measured and simulated (as in Fig. 1) curves of the transmission response for the broadband on/off THz filter. The agreement between the two curves is good but most important, the on and off behaving of the filter as the VO_2 temperature is at 24 and 90 °C is quite clear. The frequency range of interest is from 0.1 to 0.6 THz. We note that the transmission peak shows high% of transmission (\sim 83%) at 0.35 THz. At 90 °C, there is some difference between measurement and simulation results. This is most likely due to ideal conductivity

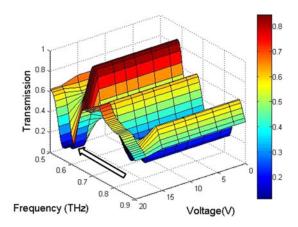


Fig. 15. Transmission of frequency shifted stopband filter versus frequency (0.5–0.9 THz) for different voltages applied to the heater.

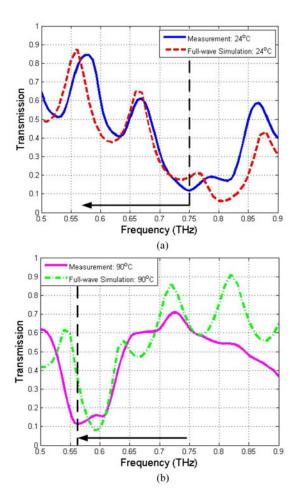


Fig. 16. Comparison of simulated and measured transmission response of the frequency reconfigurable stopband THz filter at (a) 24 °C and (b) 90 °C.

used in the simulation and the actual material used in fabrication. In addition, the Fabry–Perot effect taking place within the sapphire substrate could lower the filter performance. As the temperature increases beyond the transition point (68 °C), the transmission peak vanishes and overall transmission drops by 20 dB. This shows the performance of switch on and switch off

functionality of the filter at 0.35 THz. Please note that the off state of this filter can be explained by a Fabry–Perot effect in the sapphire substrate. In order to avoid the evanescent waves to propagate through FSS structure, the thickness of the dielectric substrate should be less than the wavelength $\lambda/20$ [27]. However, due to the lack of availability of thinner sapphire substrate, 150- μ m thick sapphire was used.

B. Frequency Reconfigurable Filter Measurement

The transmission responses of the reconfigurable stopband filter as a function of the applied voltage to the heater is plotted in Fig. 15. It is observed that the stopband is shifted downward from 0.75 to 0.55 THz at 18 V. Fig. 16(a) shows the comparison between measurement and simulation (as in Fig. 2) at 24 °C. There is a small shift from 0.8 to 0.75 THz and the bandwidth is broader. At 90 °C, the stopband peak is shifted to 0.55 from 0.6 THz. This difference between the measured and simulation results can be attributed to the minor misalignment during the fabrication processes and the undercut while etching the VO₂ patterns. However, the measured responses still shows a large shift (\sim 0.2 THz) as the temperature increases above the transition temperature. This design can be considered as an experimental demonstration for the frequency reconfigurable stopband THz filter in the range of 0.5–0.9 THz.

V. CONCLUSION AND FUTURE WORK

We developed and measured the reconfigurable THz filters using FSS and PCM: VO2 integrated with heater. The goal was for an excellent transmission of THz filter with reconfigurable properties to improve THz applications' selectivity. Two designs are achieved here as broadband on/off THz filter and frequency reconfigurable stopband THz filter. For on/off filter, the VO₂ thin film is deposited between FSS pattern and substrate. The peak frequency of this reconfigurable THz filter is at 0.35 THz and the peak is suppressed when the temperature increases beyond the transition temperature (68 °C). For stopband filter, the VO₂ thin film is patterned as part of the FSS structure. There is a shift of frequency from 0.75 down to 0.55 THz as temperature increased above 68 °C. Further, the integrated heater is first introduced here to provide practical realization for reconfigured filter with high performance. Such filters are great candidates for next-generation THz sensing, spectroscopy, and imaging applications. Although only a specified range of frequency and only VO₂ were considered here, improved filter designs with different design geometries, other selected materials, and substrates could allow for different frequency ranges and higher filter performances. In addition, the heater can be further optimized to provide faster speed and better temperature control.

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